#### **Power Plane and D li ecoupling O ptimization** Isaac Waldron



#### **Overview**

- **Frequency- and time-domain power**  $\blacksquare$ distribution system specifications
- **Decoupling design example** 
	- **Bare board**
	- Added capacitors
	- **Buried Capacitance**
- **Conclusion**





#### **Frequency Domain PDS Targets**

- $\mathcal{L}_{\mathcal{A}}$  Excessive impedance seen by a device drawing power from a PDS will cause power voltage to fluctuate
- On a board, impedance must be below target from DC to several hundred MHz
- **Working in the frequency domain allows quick** estimation of power quality











# **Time Domain PDS Targets**

- **- S-parameters and impedance are** calculated in the frequency domain
- Device specifications are typically given in in the time domain
- **Example: maximum VCC excursion 10%** of nominal value
	- 1.8 V VCC has an allowable range of 1.62 V to 1.98 V









#### **Board Imported from Layout**



**Measuring** impedance at the six VCC pins on U41



#### **Defining the Target Impedance**



- **To define the target** impedance we need to consider two **VRM** factors:
	- Peak current
		- **Determines maximum** impedance
	- **Spectral power** 
		- **Determines cutoff** frequency



#### **Peak Current**

- Peak current 37.87 mA
- maximum voltage swing:

$$
\frac{0.18 \text{ V}}{6(37.87 \text{ mA})} = 800 \text{ m}\Omega
$$





#### **Driver Spectrum**













#### **Bare Board**













#### **Time Domain Schematic**





termination used as load for PDS

Package decoupling modeled using a capacitor w/ ESR, ESL





## **Switching Power Noise**







#### **Spectral Analysis**











### **Adding Bulk Capacitors**

Added two 47 uF capacitors as specified by VRM manufacturer









![](_page_18_Picture_2.jpeg)

![](_page_18_Picture_3.jpeg)

#### **Bare Board vs. Bulk Capacitors Capacitors**

![](_page_19_Figure_1.jpeg)

![](_page_19_Picture_2.jpeg)

![](_page_19_Picture_3.jpeg)

#### **Bulk Capacitors**

![](_page_20_Figure_1.jpeg)

![](_page_20_Picture_2.jpeg)

![](_page_20_Picture_3.jpeg)

![](_page_21_Figure_1.jpeg)

![](_page_21_Picture_2.jpeg)

![](_page_21_Picture_3.jpeg)

# **Switching Power Noise**

![](_page_22_Figure_1.jpeg)

![](_page_22_Picture_2.jpeg)

![](_page_22_Picture_3.jpeg)

#### **Spectral Analysis**

![](_page_23_Figure_1.jpeg)

![](_page_23_Picture_2.jpeg)

#### **Resonance at 50 MHz 50**

![](_page_24_Picture_1.jpeg)

![](_page_24_Picture_2.jpeg)

![](_page_24_Picture_3.jpeg)

![](_page_25_Figure_1.jpeg)

![](_page_25_Picture_2.jpeg)

![](_page_25_Picture_3.jpeg)

#### **Choosing <sup>a</sup> Capacitor**

■ To reduce the effect *a* **<b>EX EX EX 22 nF** of a resonance, choose a capacitor with a low impedance at the resonant frequency

![](_page_26_Figure_2.jpeg)

![](_page_26_Picture_3.jpeg)

![](_page_26_Picture_4.jpeg)

### **Added HF Capacitors**

■ 52 20 nF capacitors were added across the board to reduce high-frequency impedance and to cancel resonance at 50 MHz

![](_page_27_Picture_2.jpeg)

![](_page_27_Picture_3.jpeg)

![](_page_28_Figure_1.jpeg)

![](_page_28_Picture_2.jpeg)

![](_page_28_Picture_3.jpeg)

## **Bulk vs. HF Capacitors 1**

![](_page_29_Figure_1.jpeg)

![](_page_29_Picture_2.jpeg)

### **HF Capacitors 1**

![](_page_30_Figure_1.jpeg)

![](_page_30_Picture_2.jpeg)

![](_page_30_Picture_3.jpeg)

![](_page_31_Figure_1.jpeg)

![](_page_31_Picture_2.jpeg)

![](_page_31_Picture_3.jpeg)

## **Switching Power Noise**

![](_page_32_Figure_1.jpeg)

![](_page_32_Picture_2.jpeg)

![](_page_32_Picture_3.jpeg)

![](_page_33_Figure_1.jpeg)

![](_page_33_Picture_2.jpeg)

![](_page_33_Picture_3.jpeg)

# **Extending Low Impedance**

- 10 1.2 nF capacitors were added across the board to extend minimum high frequency impedance
- 1.2 nF capacitor was **Ky** Added capacitors chosen due to low impedance at 200 MHz
- 4 of these were located near U41

![](_page_34_Picture_4.jpeg)

![](_page_34_Picture_5.jpeg)

![](_page_35_Figure_1.jpeg)

![](_page_35_Picture_2.jpeg)

![](_page_35_Picture_3.jpeg)

#### **HF 1 vs. HF 2**

![](_page_36_Figure_1.jpeg)

![](_page_36_Picture_2.jpeg)

![](_page_36_Picture_3.jpeg)

### **HF 2**

![](_page_37_Figure_1.jpeg)

![](_page_37_Picture_2.jpeg)

![](_page_37_Picture_3.jpeg)

![](_page_38_Figure_1.jpeg)

![](_page_38_Picture_2.jpeg)

![](_page_38_Picture_3.jpeg)

## **Switching Power Noise**

![](_page_39_Figure_1.jpeg)

![](_page_39_Picture_2.jpeg)

![](_page_39_Picture_3.jpeg)

#### **Resonance at 80 MHz**

![](_page_40_Picture_1.jpeg)

![](_page_40_Picture_2.jpeg)

![](_page_40_Picture_3.jpeg)

![](_page_41_Figure_1.jpeg)

![](_page_41_Picture_2.jpeg)

![](_page_41_Picture_3.jpeg)

#### **Removing <sup>a</sup> Resonance**

![](_page_42_Picture_1.jpeg)

■ Six 8 nF capacitors were added near U41 to cancel resonance at 80 MHz

![](_page_42_Picture_3.jpeg)

![](_page_42_Picture_4.jpeg)

#### **Choosing <sup>a</sup> Capacitor**

**• To reduce the effect EXECUTE:** 8.2 nF of a resonance, choose a capacitor with a low impedance at the resonant frequency

![](_page_43_Figure_2.jpeg)

![](_page_43_Picture_3.jpeg)

![](_page_43_Picture_4.jpeg)

![](_page_44_Figure_1.jpeg)

![](_page_44_Picture_2.jpeg)

![](_page_44_Picture_3.jpeg)

#### **HF 2 vs. HF 3**

![](_page_45_Figure_1.jpeg)

![](_page_45_Picture_2.jpeg)

#### **HF 3**

![](_page_46_Figure_1.jpeg)

![](_page_46_Picture_2.jpeg)

![](_page_46_Picture_3.jpeg)

![](_page_47_Figure_1.jpeg)

![](_page_47_Picture_2.jpeg)

![](_page_47_Picture_3.jpeg)

#### **Switching Power Noise** the contract of the contract of

![](_page_48_Figure_1.jpeg)

![](_page_48_Picture_2.jpeg)

![](_page_48_Picture_3.jpeg)

![](_page_49_Figure_1.jpeg)

![](_page_49_Picture_2.jpeg)

![](_page_49_Picture_3.jpeg)

### **Buried Capacitance**

- Due to parasitic inductance it will be impossible to further decouple the board with capacitors
- Using a thinner dielectric layer between power and ground planes introduces additional capacitance and reduces high frequency impedance

Capacitance of  
parallel plates: 
$$
C = \varepsilon \frac{A}{d}
$$

![](_page_50_Picture_4.jpeg)

![](_page_50_Picture_5.jpeg)

![](_page_51_Figure_1.jpeg)

![](_page_51_Picture_2.jpeg)

![](_page_51_Picture_3.jpeg)

### **HF 3 vs. Buried Capacitance**

![](_page_52_Figure_1.jpeg)

![](_page_52_Picture_2.jpeg)

#### **Buried Capacitance**

![](_page_53_Figure_1.jpeg)

![](_page_53_Picture_2.jpeg)

![](_page_54_Figure_1.jpeg)

![](_page_54_Picture_2.jpeg)

![](_page_54_Picture_3.jpeg)

#### **Switching Power Noise** the contract of the contract of

![](_page_55_Figure_1.jpeg)

![](_page_55_Picture_2.jpeg)

![](_page_55_Picture_3.jpeg)

#### **Conclusion**

- Ansoft software allows PCB engineers to design effective decoupling solutions for their PCBs
- **Impedance and resonant mode simulations** connect the frequency domain to the spatial domain and allow selection of capacitor value and placement
- *Frequency domain* extractions are useful for quickly optimizing PDS designs, but time *domain* simulations are necessary to ensure compliance with device specs

![](_page_56_Picture_4.jpeg)